Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	30	silicon with wafer with sensor$4 with top with bottom	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 08:25
L3	571	702/56	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 08:25
S1	168	wafer with sensor$4 with top with bottom	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/01 13:21
S3	26	silicon with wafer with sensor$4 with top with bottom	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 08:24
S11	2	wafer with thickn$4 with sensor$4 with (build$4 or fabricat$4) with top with bottom	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/01 13:41
S18	17	silicon with sensor$4 with (build$4 or fabricat$4) with top with bottom	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/01 13:47